

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Mou-Shiung LIN	01/22/2008
RECEIVING PARTY DATA	
Name:	Megica Corporation
Street Address:	ROOM 301/ 302, NO.47, PARK 2ND RD., SCIENCE-BASED INDUSTRIAL PARK
City:	HSINCHU
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13071203
CORRESPONDENCE DATA	
Fax Number:	3102015219
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	310 277 7200
Email:	qualcomm-uspto@seyfarth.com
Correspondent Name:	Qualcomm Incorporated/Seyfarth Shaw LLP
Address Line 1:	2029 Century Park East, Suite 3500
Address Line 4:	Los Angeles, CALIFORNIA 90067-3021
ATTORNEY DOCKET NUMBER:	092990D1B1C1C1C1
NAME OF SUBMITTER:	Joseph Lutz
Signature:	/Joseph Lutz/
Date:	05/07/2013
Total Attachments: 2 source=092990D1B1C1C1C1-Assignment_AsFiled_07Ma2013#page1.tif source=092990D1B1C1C1C1-Assignment_AsFiled_07Ma2013#page2.tif	

CH \$40.00 13071203

PATENT

# ASSIGNMENT

WHEREAS,

1 Mou-Shiung Lin

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: Post passivation interconnection schemes on top of the IC chips

☐ Filed:

Serial No

☒ Executed concurrently with the execution of this instrument

WHEREAS, Megica Corporation  
of Room 301/302, No 47, Park 2nd Rd, Science-Based Industrial Park Hsinchu,  
Taiwan, R O C

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U S Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns

## ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated

Signature: Mou-Shiung Lin

Date: Jan. 22, 2008

Sole or First Joint Inventor Mou-Shiung Lin